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Semiconductor devices - Guidelines for reliability qualification plans - Part 2: Concept of mission profile

Táto norma obsahuje anglickú verziu európskej normy.  
This standard includes the English version of the European Standard.

Táto norma bola oznámená vo Vestníku ÚNMS SR č. 08/23

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EUROPEAN STANDARD

**EN IEC 63287-2**

NORME EUROPÉENNE

EUROPÄISCHE NORM

May 2023

ICS 31.080.01

English Version

**Semiconductor devices - Guidelines for reliability qualification plans - Part 2: Concept of mission profile  
(IEC 63287-2:2023)**

Dispositifs à semiconducteurs - Lignes directrices  
concernant les plans de qualification de la fiabilité - Partie 2:  
Concept de profil de mission  
(IEC 63287-2:2023)

Halbleiterbauelemente - Richtlinien für  
Zuverlässigkeitsqualifizierungspläne - Teil 2: Konzept des  
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(IEC 63287-2:2023)

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**EN IEC 63287-2:2023 (E)****European foreword**

The text of document 47/2796/FDIS, future edition 1 of IEC 63287-2, prepared by IEC/TC 47 "Semiconductor devices" was submitted to the IEC-CENELEC parallel vote and approved by CENELEC as EN IEC 63287-2:2023.

The following dates are fixed:

- latest date by which the document has to be implemented at national level by publication of an identical national standard or by endorsement (dop) 2024-02-03
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IEC 60068-2-1 NOTE Approved as EN 60068-2-1

IEC 60068-2-30 NOTE Approved as EN 60068-2-30

IEC 60749-11 NOTE Approved as EN 60749-11

## **Annex ZA** (normative)

### **Normative references to international publications with their corresponding European publications**

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| <u>Publication</u> | <u>Year</u> | <u>Title</u>   | <u>EN/HD</u>   | <u>Year</u> |
|--------------------|-------------|--|----------------|-------------|
| IEC 63287-1        | 2021        | Semiconductor devices - Generic semiconductor qualification guidelines - Part 1: Guidelines for IC reliability qualification | EN IEC 63287-1 | 2021        |





IEC 63287-2

Edition 1.0 2023-03

# INTERNATIONAL STANDARD

# NORME INTERNATIONALE



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**Semiconductor devices – Guidelines for reliability qualification plans –  
Part 2: Concept of mission profile**

**Dispositifs à semiconducteurs – Lignes directrices concernant les plans de  
qualification de la fiabilité –  
Partie 2: Concept de profil de mission**





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IEC 63287-2

Edition 1.0 2023-03

# INTERNATIONAL STANDARD

# NORME INTERNATIONALE



**Semiconductor devices – Guidelines for reliability qualification plans –  
Part 2: Concept of mission profile**

**Dispositifs à semiconducteurs – Lignes directrices concernant les plans de  
qualification de la fiabilité –  
Partie 2: Concept de profil de mission**

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**SEMICONDUCTOR DEVICES –  
GUIDELINES FOR RELIABILITY QUALIFICATION PLANS –**
**Part 2: Concept of mission profile****FOREWORD**

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|              |                  |
|--------------|------------------|
| Draft        | Report on voting |
| 47/2796/FDIS | 47/2803/RVD      |

Full information on the voting for its approval can be found in the report on voting indicated in the above table.

The language used for the development of this International Standard is English.

This document was drafted in accordance with ISO/IEC Directives, Part 2, and developed in accordance with ISO/IEC Directives, Part 1 and ISO/IEC Directives, IEC Supplement, available at [www.iec.ch/members\\_experts/refdocs](http://www.iec.ch/members_experts/refdocs). The main document types developed by IEC are described in greater detail at [www.iec.ch/standardsdev/publications](http://www.iec.ch/standardsdev/publications).

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## **SEMICONDUCTOR DEVICES – GUIDELINES FOR RELIABILITY QUALIFICATION PLANS –**

### **Part 2: Concept of mission profile**

#### **1 Scope**

This part of IEC 63287 gives guidelines for the development of reliability qualification plans using the concept of mission profile, based on the environmental conditioning and proposed usage of the product. This document is not intended for military- and space-related applications.

#### **2 Normative references**

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IEC 63287-1:2021, *Semiconductor devices – Generic semiconductor qualification guidelines – Part 1: Guidelines for IC reliability qualification*

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